Integrated Silicon Pressure Sensor On-Chip Signal Conditioned, Temperature Compensated and Calibrated

MPX5500 SERIES

INTEGRATED PRESSURE SENSOR 0 to 500 kPa (0 to 72.5 psi) 0.2 to 4.7 Volts Output

The MPX5500 series piezoresistive transducer is a state–of–the–art monolithic silicon pressure sensor designed for a wide range of applications, but particularly those employing a microcontroller or microprocessor with A/D inputs. This patented, single element transducer combines advanced micromachining techniques, thin–film metallization, and bipolar processing to provide an accurate, high level analog output signal that is proportional to the applied pressure.

Features

- 2.5% Maximum Error over 0° to 85°C
- Ideally suited for Microprocessor or Microcontroller–Based Systems
- Patented Silicon Shear Stress Strain Gauge
- Durable Epoxy Unibody Element
- Available in Differential and Gauge Configurations

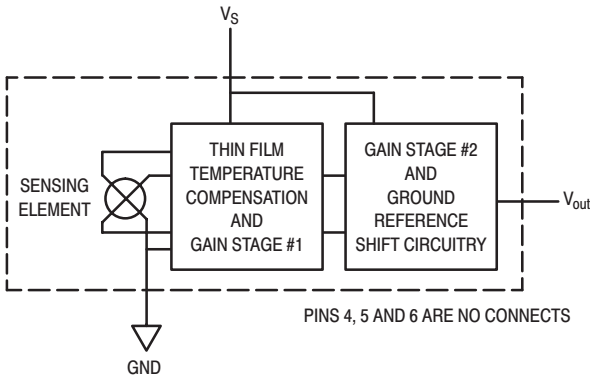
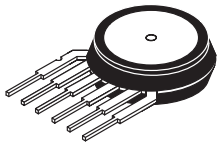
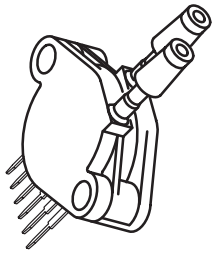


Figure 1. Fully Integrated Pressure Sensor Schematic



MPX5500D
CASE 867



MPX5500DP
CASE 867C

PIN NUMBER			
1	V_{out}	4	N/C
2	Gnd	5	N/C
3	V_S	6	N/C

NOTE: Pins 4, 5, and 6 are internal device connections. Do not connect to external circuitry or ground. Pin 1 is noted by the notch in the lead.

MAXIMUM RATINGS(1)

Parametrics	Symbol	Value	Unit
Maximum Pressure(2) (P2 ≤ 1 Atmosphere)	$P1_{max}$	2000	kPa
Storage Temperature	T_{stg}	–40° to +125°	°C
Operating Temperature	T_A	–40° to +125°	°C

NOTES:
1. Maximum Ratings apply to Case 867 only. Extended exposure at the specified limits may cause permanent damage or degradation to the device.
2. This sensor is designed for applications where P1 is always greater than, or equal to P2. P2 maximum is 500 kPa.

OPERATING CHARACTERISTICS (V_S = 5.0 Vdc, T_A = 25°C unless otherwise noted, P1 > P2. Decoupling circuit shown in Figure 4 required to meet electrical specifications.)

Characteristic		Symbol	Min	Typ	Max	Unit
Pressure Range(1)		P_{OP}	0	—	500	kPa
Supply Voltage(2)		V_S	4.75	5.0	5.25	Vdc
Supply Current		I_o	—	7.0	10.0	mAdc
Zero Pressure Offset(3)	(0 to 85°C)	V_{off}	0.088	0.20	0.313	Vdc
Full Scale Output(4)	(0 to 85°C)	V_{FSO}	4.587	4.70	4.813	Vdc
Full Scale Span(5)	(0 to 85°C)	V_{FSS}	—	4.50	—	Vdc
Accuracy(6)		—	—	—	±2.5	$\%V_{FSS}$
Sensitivity		V/P	—	9.0	—	mV/kPa
Response Time(7)		t_R	—	1.0	—	ms
Output Source Current at Full Scale Output		I_o+	—	0.1	—	mAdc
Warm–Up Time(8)		—	—	20	—	ms

NOTES:
1. 1.0kPa (kiloPascal) equals 0.145 psi.
2. Device is ratiometric within this specified excitation range.
3. Offset (V_{off}) is defined as the output voltage at the minimum rated pressure.
4. Full Scale Output (V_{FSO}) is defined as the output voltage at full rated pressure.
5. Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
6. Accuracy (error budget) consists of the following:
   - Linearity: Output deviation from a straight line relationship with pressure over the specified pressure range.
   - Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.
   - Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from minimum or maximum rated pressure at 25°C.
   - TcSpan: Output deviation over the temperature range of 0° to 85°C, relative to 25°C.
   - TcOffset: Output deviation with minimum pressure applied, over the temperature range of 0° to 85°C, relative to 25°C.
   - Variation from Nominal: The variation from nominal values, for Offset or Full Scale Span, as a percent of V_{FSS} at 25°C.
7. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
8. Warm–up Time is defined as the time required for the device to meet the specified output voltage after the pressure has been stabilized.

MECHANICAL CHARACTERISTICS

Characteristics	Typ	Unit
Weight, Basic Element (Case 867)	4.0	grams

Figure 3 illustrates the Differential/Gauge basic chip carrier (Case 867). A fluorosilicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the sensor diaphragm. (For use of the MPX5500D in a high pressure, cyclic application, consult the factory.)

The MPX5500 series pressure sensor operating characteristics, and internal reliability and qualification tests are based on use of dry air as the pressure media. Media, other than dry air, may have adverse effects on sensor performance and long–term reliability. Contact the factory for information regarding media compatibility in your application.

Figure 2 shows the sensor output signal relative to pressure input. Typical, minimum, and maximum output curves are shown for operation over a temperature range of 0° to 85°C using the decoupling circuit shown in Figure 4. The output will saturate outside of the specified pressure range.

Figure 4 shows the recommended decoupling circuit for interfacing the output of the integrated sensor to the A/D input of a microprocessor or microcontroller. Proper decoupling of the power supply is recommended.

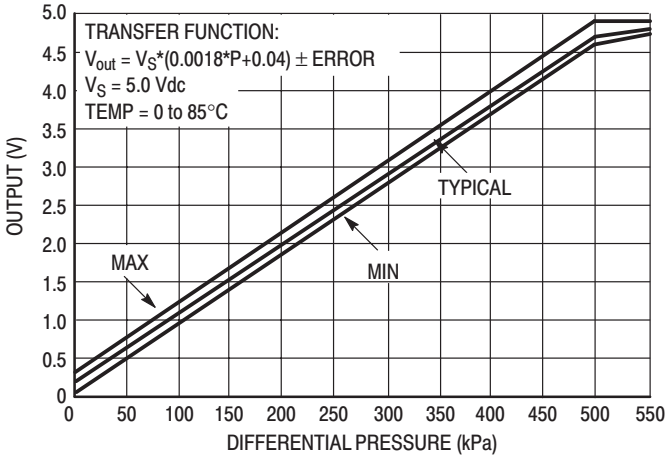


Figure 2. Output versus Pressure Differential

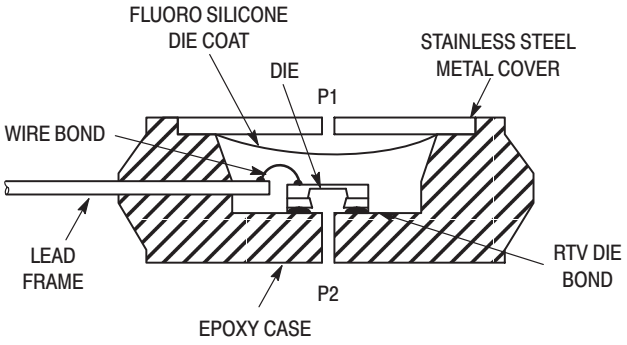


Figure 3. Cross–Sectional Diagram (Not to Scale)

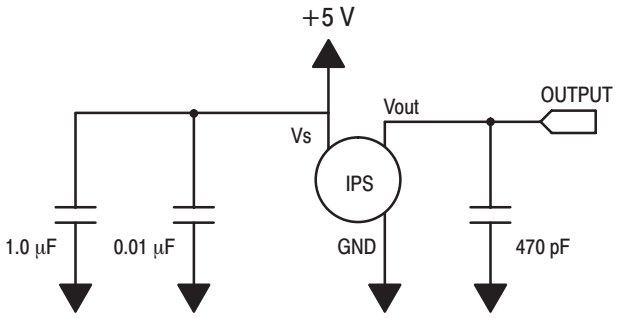


Figure 4. Recommended power supply decoupling and output filtering.
For additional output filtering, please refer to Application Note AN1646.

PRESSURE (P1)/VACUUM (P2) SIDE IDENTIFICATION TABLE

Motorola designates the two sides of the pressure sensor as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing fluorosilicone gel which protects the die from the environment. The Motorola MPX pressure sensor is designed to operate with positive differential pressure applied, P1 > P2.

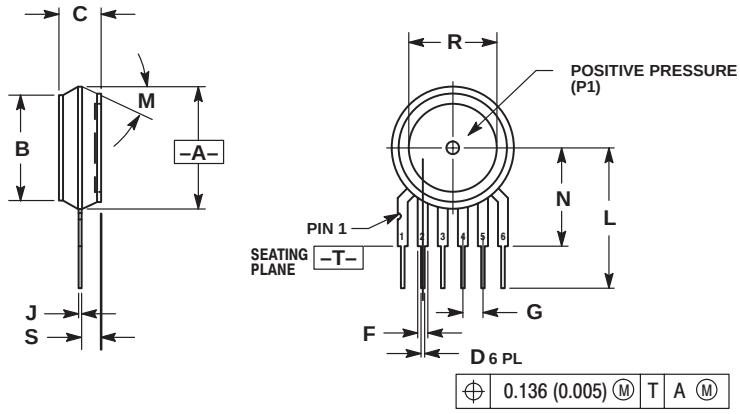
The Pressure (P1) side may be identified by using the Table below:

Part Number	Case Type	Pressure (P1) Side Identifier
MPX5500D	867	Stainless Steel Cap
MPX5500DP	867C	Side with Part Marking

ORDERING INFORMATION

Device Name	Options	Case Type	MPX Series	
			Order Number	Device Marking
Basic Element	Differential	867	MPX5500D	MPX5500D
Ported Elements	Differential Dual Ports	867C	MPX5500DP	MPX5500DP

PACKAGE DIMENSIONS



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION –A– IS INCLUSIVE OF THE MOLD STOP RING. MOLD STOP RING NOT TO EXCEED 16.00 (0.630).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.595	0.630	15.11	16.00
B	0.514	0.534	13.06	13.56
C	0.200	0.220	5.08	5.59
D	0.027	0.033	0.68	0.84
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.40
L	0.695	0.725	17.65	18.42
M	30 °NOM		30 °NOM	
N	0.475	0.495	12.07	12.57
R	0.430	0.450	10.92	11.43
S	0.090	0.105	2.29	2.66

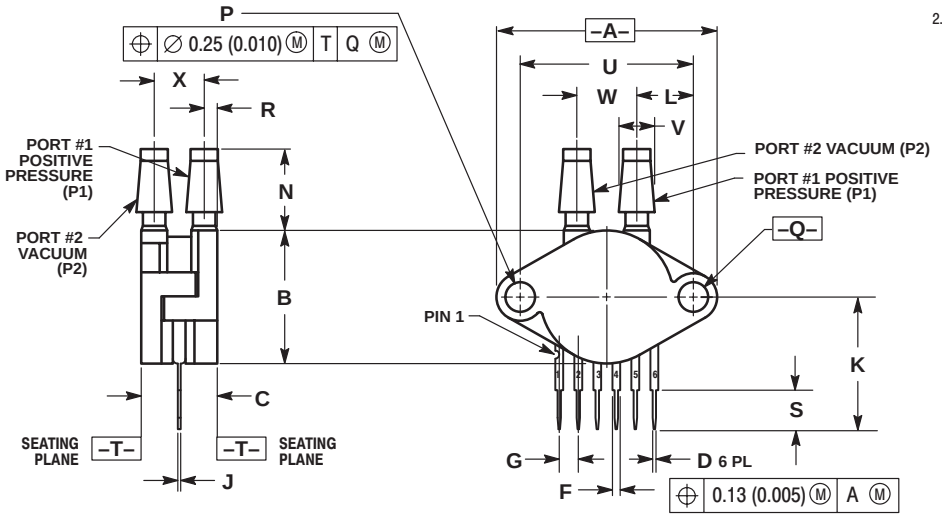
STYLE 1:
PIN 1. VOUT
2. GROUND
3. VCC
4. V1
5. V2
6. VEX

STYLE 2:
PIN 1. OPEN
2. GROUND
3. –VOUT
4. VSUPPLY
5. +VOUT
6. OPEN

STYLE 3:
PIN 1. OPEN
2. GROUND
3. +VOUT
4. +VSUPPLY
5. –VOUT
6. OPEN

CASE 867–08
ISSUE N

BASIC ELEMENT



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	1.145	1.175	29.08	29.85
B	0.685	0.715	17.40	18.16
C	0.405	0.435	10.29	11.05
D	0.027	0.033	0.68	0.84
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.41
K	0.695	0.725	17.65	18.42
L	0.290	0.300	7.37	7.62
N	0.420	0.440	10.67	11.18
P	0.153	0.159	3.89	4.04
Q	0.153	0.159	3.89	4.04
R	0.063	0.083	1.60	2.11
S	0.220	0.240	5.59	6.10
U	0.910 BSC		23.11 BSC	
V	0.182	0.194	4.62	4.93
W	0.310	0.330	7.87	8.38
X	0.248	0.278	6.30	7.06

STYLE 1:
PIN 1. V_{OUT}
2. GROUND
3. V_{CC}
4. V1
5. V2
6. V_{EX}

CASE 867C–05
ISSUE F

PRESSURE AND VACUUM SIDES PORTED (DP)

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